

SPEC SHEET (FOR REFERENCE)	SHEET No.	Rev.	Page.
	G05072A		1 of 1

TYPE : 6PC2106N3T**

CHIP SIZE	0.38 * 0.38 mm
WAFER SIZE	6 inch
POSSIBLE DIE PER WAFER	106,200 pcs

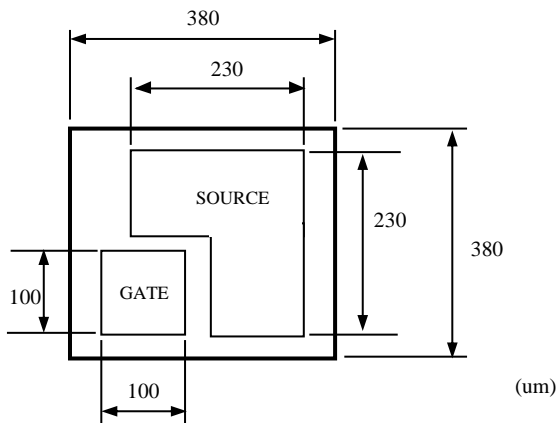
Maximum Ratings (Ta=25°C)

Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	60	V
Gate-source voltage	VGSS	±20	V
Drain Current (DC)	ID	0.3	A

* For Reference

WAFER PROBING SPEC (Ta=25°C)

No	MODE	LIMIT				CONDITIONS
		MIN.	Typ	MAX.	UNIT	
1	IGSS			±10	nA	VGS= ±20V VDS= 0V
2	IDSS			1	uA	VDS= 60V VGS= 0V
3	BVDSS	63			V	ID= 10uA
4	VTH	1.2	1.6	2.0	V	ID= 250uA VDS=VGS
5	RDS(on)1		1.4	2.0	Ω	ID= 100mA VGS= 5.0V
6	RDS(on)2		1.1	1.6	Ω	ID= 500mA VGS= 10V
7	VSD	0.5		1.1	V	I= 115mA VGS= 0V



NOTE: